

## Description

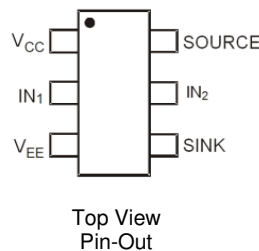
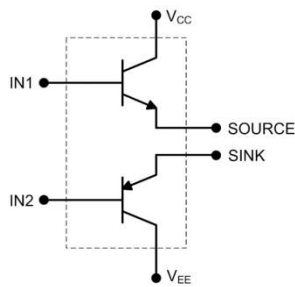
The ZXGD3004E6 is a high-speed, non-inverting single gate driver designed for switching MOSFETs or IGBTs. It can transfer up to 8A peak source/source current into the gate for effective charging and discharging of the capacitive gate load.

This gate driver ensures rapid switching of the MOSFET to minimize power losses and distortion in high current switching applications. It can typically drive 1.9A into the low gate impedance with just 10mA input from a controller. The turn-on and turn-off switching behaviour of the MOSFET can be individually tailored to suit an application. By defining the switching characteristics appropriately, EMI and cross conduction can be reduced.

## Applications

Gate Driving Power MOSFET and IGBTs in:

- AC-DC Power Supplies (SMPS)
- DC-DC Converters
- DC-AC Inverters (i.e. Solar)
- 1, 2 and 3-Phase Motor Control Circuits
- Amplifier Output Stages



Pin Name	Pin Function
V <sub>CC</sub>	Driver Supply High
IN <sub>1</sub> & IN <sub>2</sub>	Driver Input *
V <sub>EE</sub>	Supply Voltage Low
SOURCE	Source Current Output **
SINK	Sink Current Output **

\* Typically connect IN<sub>1</sub> & IN<sub>2</sub> together

\*\* Typically connect SOURCE & SINK together

## Features

- High-Gain Buffer with Typically 1.9A Output from 10mA Input
- 8 Amps Peak Output Current
- 40V Supply for +20V to -18V Gate Driving to Prevent dV/dt Induced False Triggering and Minimize On-Losses
- Emitter-Follower that is Rugged to Latch-Up/Shoot-Through
- Fast Switching Emitter-Follower Configuration
  - 1ns Propagation Delay Time
  - 14ns Rise/Fall Time, 1500pF load
- Optimized Pin-Out to Simplify PCB Layout and Reduce Parasitic Trace Inductances
- Near-Zero Quiescent Supply Current
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **An Automotive-Compliant Part is Available Under Separate Datasheet ([ZXGD3004E6Q](#))**

## Mechanical Data

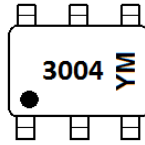
- Case: SOT26
- Case Material: Molded Plastic. "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 Ⓔ3
- Weight: 0.018 grams (Approximate)

## Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
ZXGD3004E6TA	AEC-Q101	3004	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free/](http://www.diodes.com/quality/lead_free/) for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
  3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information

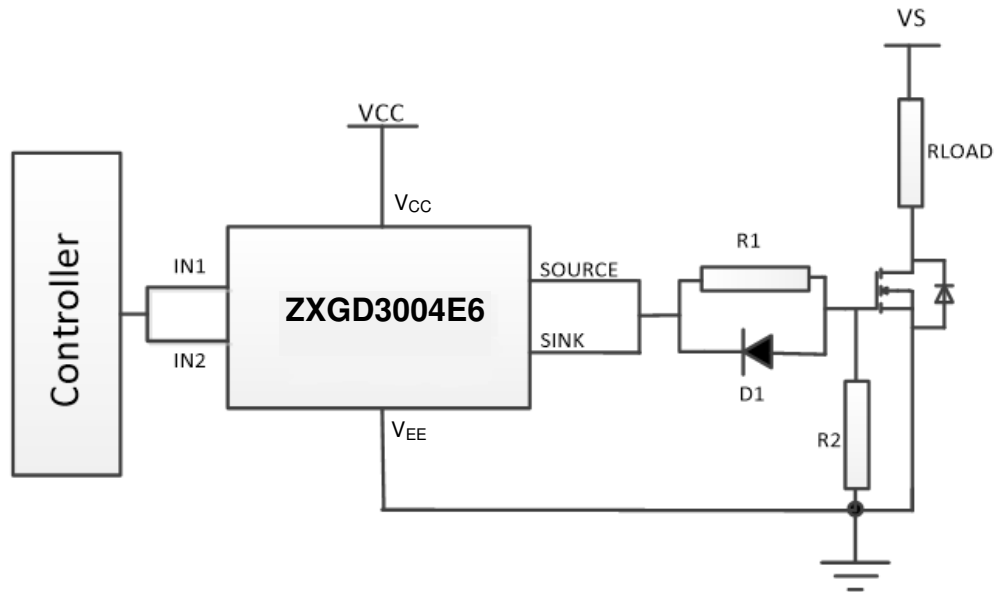


3004 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: F = 2018)  
 M = Month (ex: 9 = September)

Date Code Key

<b>Year</b>	2018		2019		2020		2021		2022		2023		2024		2025	
<b>Code</b>	F		G		H		I		J		K		L		M	
<b>Month</b>	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec				
<b>Code</b>	1	2	3	4	5	6	7	8	9	O	N	D				

## Typical Application Circuit



R1, D1 combination can be used for variable turn on and turn off times.

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage, with Respect to V <sub>EE</sub>	V <sub>CC</sub>	40	V
Input Voltage, with Respect to V <sub>EE</sub>	V <sub>IN</sub>	40	V
Output Difference Voltage (Source – Sink)	ΔV <sub>(SOURCE-SINK)</sub>	±7	V
Peak Pulsed Output Current (Source – Sink)	I <sub>OM</sub>	±8	A
Peak Pulsed Input Current	I <sub>IN1</sub> , I <sub>IN2</sub>	±1	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Notes 5 & 6)	P <sub>D</sub>	1.1	W
Linear Derating Factor		8.8	mW/°C
Thermal Resistance, Junction to Ambient (Notes 5 & 6)	R <sub>θJA</sub>	113	°C/W
Thermal Resistance, Junction to Lead (Note 7)	R <sub>θJL</sub>	105	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

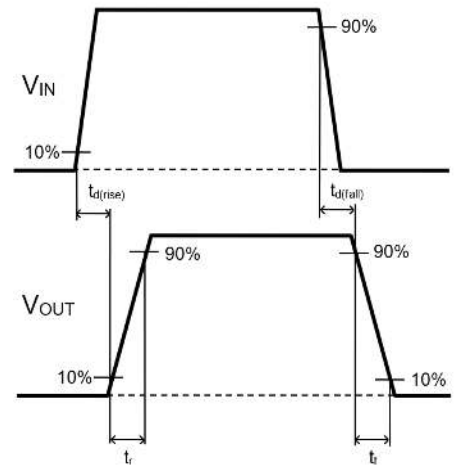
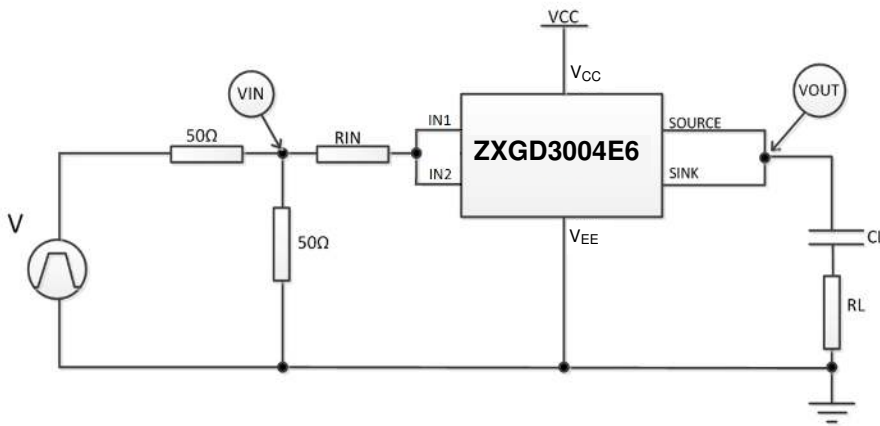
**ESD Ratings** (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C
Electrostatic Discharge – Charged Device Model	ESD CDM	1,000	V	IV

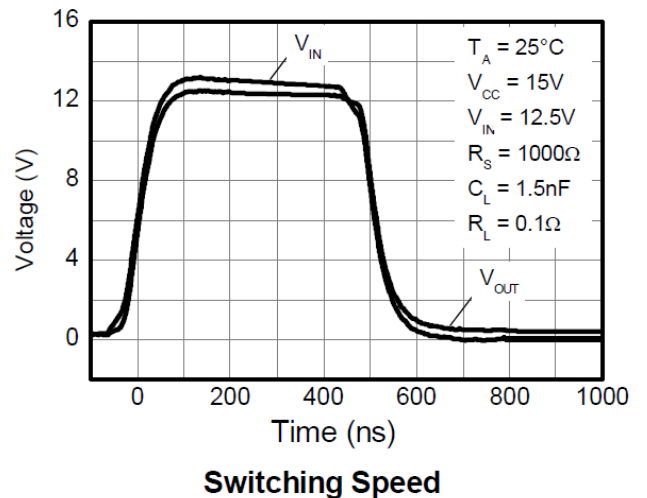
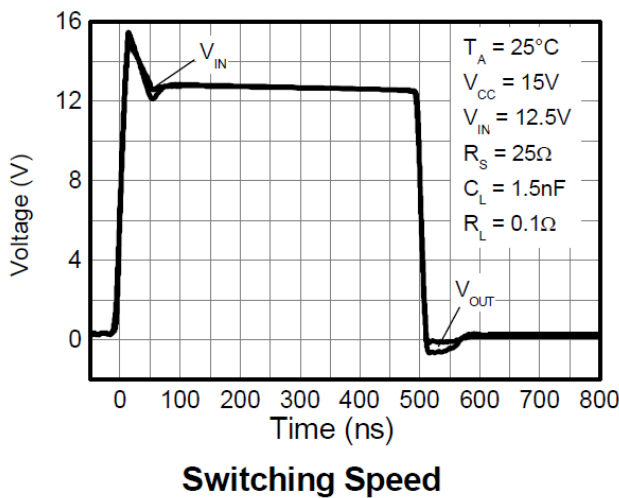
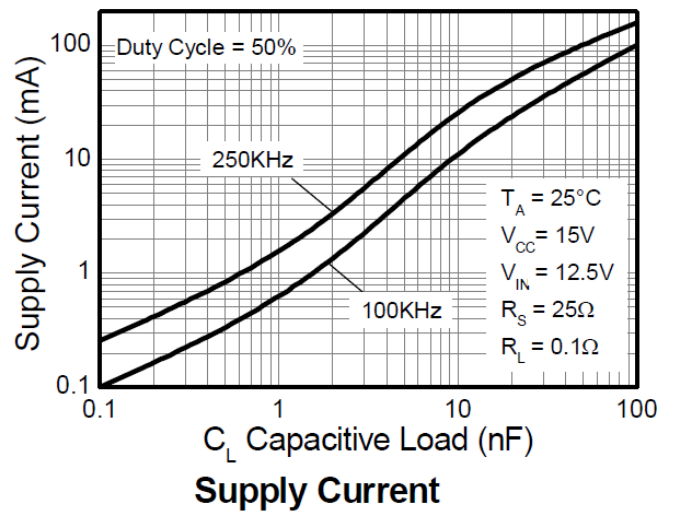
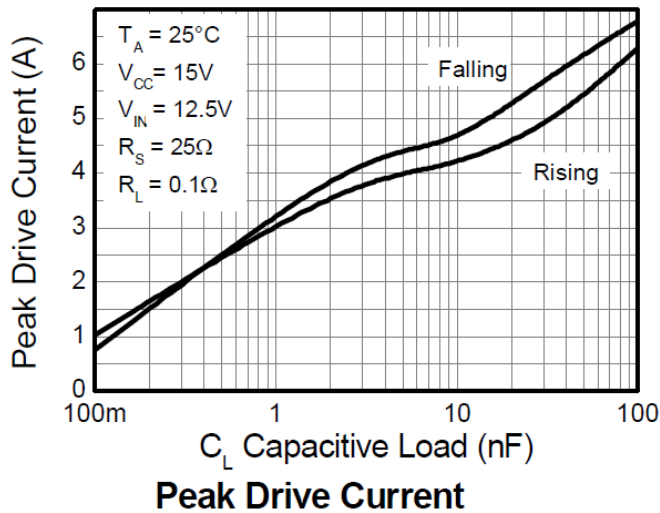
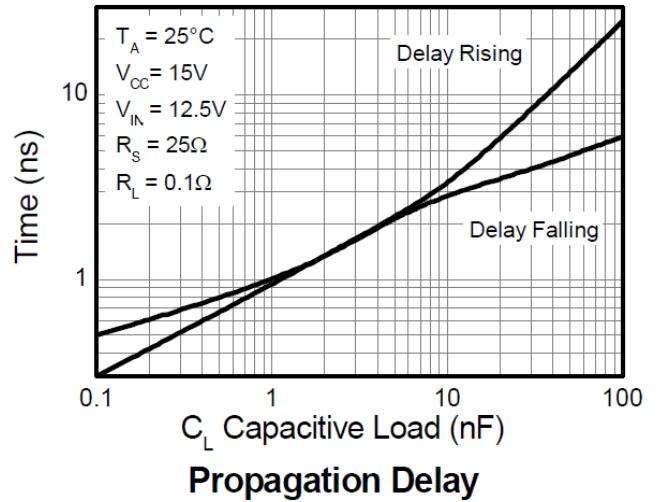
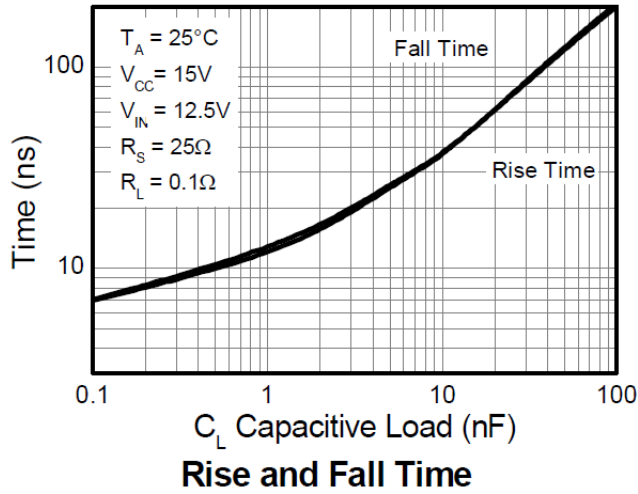
- Notes:
- For a device mounted on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state. The heatsink is split in half with the pin 1 (V<sub>CC</sub>) and pin 3 (V<sub>EE</sub>) connected separately to each half.
  - For device with two active die running at equal power.
  - Thermal resistance from junction to solder-point at the end of each lead on pin 1 (V<sub>CC</sub>) and pin 3 (V<sub>EE</sub>).
  - Refer to JEDEC specification JESD22-A114, JESD22-A115 and JESD22-C101.

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

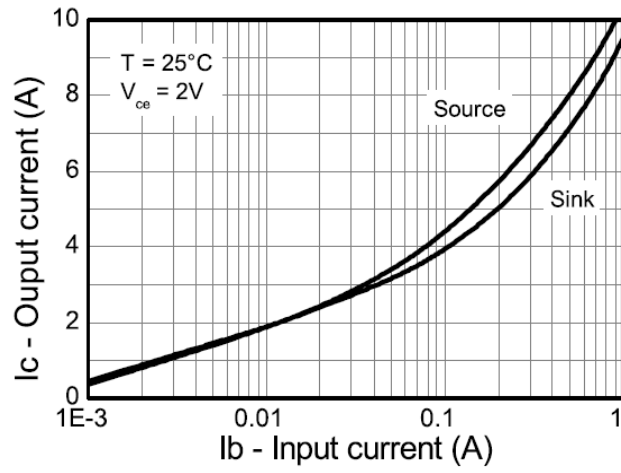
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Output Voltage, High	$V_{\text{OUT(hi)}}$	—	$V_{\text{IN1}} - 0.4$	—	V	$I_{\text{source}} = 1\mu\text{A}$
Output Voltage, Low	$V_{\text{OUT(low)}}$	—	$V_{\text{IN1}} + 0.4$	—		$I_{\text{sink}} = 1\mu\text{A}$
Source Output Leakage Current	$I_{\text{L(source)}}$	—	—	1	$\mu\text{A}$	$V_{\text{CC}} = 40\text{V}$ , $V_{\text{IN1}} = V_{\text{IN2}} = 0\text{V}$
Sink Output Leakage Current	$I_{\text{L(sink)}}$	—	—	1	$\mu\text{A}$	$V_{\text{CC}} = 40\text{V}$ , $V_{\text{IN1}} = V_{\text{IN2}} = V_{\text{CC}}$
Quiescent Supply Current	$I_{\text{Q}}$	—	—	50	nA	$V_{\text{CC}} = 32\text{V}$ , $V_{\text{IN1}} = V_{\text{IN2}} = 0\text{V}$
Peak Pulsed Source Output Current	$I_{\text{(source)M}}$	1.2	1.9	—	A	$I_{\text{IN1}} + I_{\text{IN2}} = 10\text{mA}$
Peak Pulsed Sink Output Current	$I_{\text{(sink)M}}$	1.2	1.9	—	A	$I_{\text{IN1}} + I_{\text{IN2}} = -10\text{mA}$
Peak Pulsed Source Output Current	$I_{\text{(source)M}}$	—	8	—	A	$I_{\text{IN1}} + I_{\text{IN2}} = 1\text{A}$
Peak Pulsed Sink Output Current	$I_{\text{(sink)M}}$	—	8	—	A	$I_{\text{IN1}} + I_{\text{IN2}} = -1\text{A}$
Gate Driver Switching Times	$t_{\text{d(rise)}}$	—	1.1	—	ns	$V_{\text{CC}} = 15\text{V}$ , $V_{\text{EE}} = 0\text{V}$ , $V_{\text{IN}} = 0$ to $12.5\text{V}$ , $C_{\text{L}} = 1.5\text{nF}$ , $R_{\text{L}} = 0.1\Omega$ , $R_{\text{IN}} = 25\Omega$
	$t_{\text{r}}$		13.4			
	$t_{\text{d(fall)}}$		0.95			
	$t_{\text{f}}$		12.4			
Gate Driver Switching Times	$t_{\text{d(rise)}}$	—	3.2	—	ns	$V_{\text{CC}} = 15\text{V}$ , $V_{\text{EE}} = 0\text{V}$ , $V_{\text{IN}} = 0$ to $12.5\text{V}$ , $C_{\text{L}} = 1.5\text{nF}$ , $R_{\text{L}} = 0.1\Omega$ , $R_{\text{IN}} = 1\text{k}\Omega$
	$t_{\text{r}}$		77.9			
	$t_{\text{d(fall)}}$		3.6			
	$t_{\text{f}}$		82			

**Switching Test Circuit and Timing Diagram**


**Typical Gate Driver Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



**Typical Gate Driver Characteristics (Cont.)**

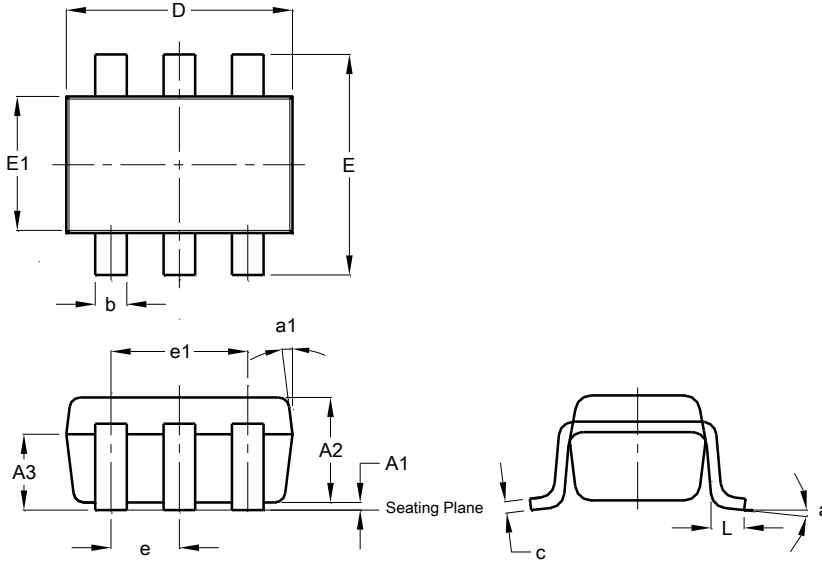


**Output current Vs Input current**

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26

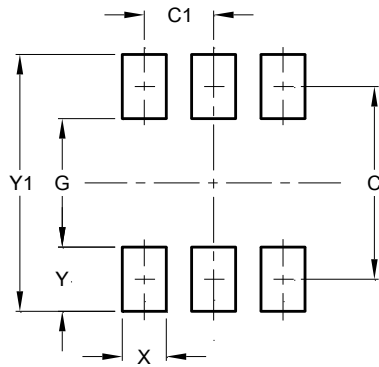


SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

**IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

**LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2018, Diodes Incorporated

[www.diodes.com](http://www.diodes.com)